

Electronic Patent Application Fee Transmittal

Application Number:				
Filing Date:				
Title of Invention:	EPOXY RESIN MOLDING MATERIAL FOR SEALING AND ELECTRONIC COMPONENT			
First Named Inventor:	Kazuyoshi Tendou			
Filer:	Joerg-Uwe V. Szpil/Bridget Burke			
Attorney Docket Number:	MIYOSH0006			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
National Stage Fee	1631	1	300	300
Natl Stage Search Fee - Report provided	1642	1	400	400
National Stage Exam - all other cases	1633	1	200	200
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				900